

PRODUCT DATA SHEET

5RMA-RC and 5RA-RC

REACH-Compliant Liquid Fluxes

Introduction

5RMA-RC and **5RA-RC** are heat-stabilized rosin fluxes designed for soldering with preforms or wire. They are formulated for use with a wide range of temperatures and metallizations. Both fluxes are free of materials listed in the REACH SVHC list (Q2, 2015).

5RMA-RC is a no-clean, mildly activated flux. **5RA-RC** is compatible with Pb-free alloys, as well as with high-Pb and SnPb alloys.

Cleaning

5RMA-RC is a no-clean flux. Removal of post reflow flux residue is usually not necessary. If cleaning is desired, commercially available flux residue removers can be used.

Because **5RA-RC** is a fully-activated flux, the post reflow residue must be removed. Solvent-based or semi-aqueous cleaners should be used to remove any flux residues.

Packaging

Standard packaging for **5RMA-RC** and **5RA-RC** is 1 U.S. pint (0.473 liter) and 1 U.S. gallon (3.785 liters).

Storage and Handling

The shelf life of **5RMA-RC** and **5RA-RC** is 1 year when stored at 0–30°C. Flux should be allowed to reach ambient temperature prior to use. Containers should be labeled with date and time of opening.

Technical Support

Indium Corporation sets the industry standard in providing rapid response, onsite technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Safety Data Sheets

The SDS for these products can be found online at <http://www.indium.com/sds>

Recommended Application Notes

- *Flux and Solder Compatibility* (Form No. 97751)
- *Common Elements* (Form No. 98557)
- *Pb-Free Solder FAQs* (Form No. 97758)
- *Practical Suggestions for Preform Design* (Form No. 97763)

Other Recommended Products

- Solder preforms
- Solder wire
- Solder research kits

	5RMA-RC Flux	5RA-RC Flux
Common Surface Metallizations	Clean copper, gold, palladium, platinum, silver, solder-plate, tin	Beryllium-copper, brass, bronze, cadmium, lead, nickel, oxidized copper, rhodium
Common Alloys to Solder	AuSn, indium alloys, SnAg, Sn63, SAC, and other Pb-free alloys	AuSn, high-lead, indium alloys, SAC and other Pb-free alloys, Sn63
Application	Dipping, spray fluxing, spin coating	Spray fluxing, spin coating, dipping
Activation	Mildly activated	Fully activated
Flash Point	12°C	12°C
Flux Type Classification	ROL1	ROH1
Solid Content	27%	21%
Typical Specific Gravity	0.865	0.857
Visual Appearance	Amber liquid	Amber liquid
Water Resistivity (Ω -cm)	>100,000	<50,000
Cleaning	Not needed	Clean for high reliability

All information is for reference only.

Not to be used as incoming product specifications.

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Contact our engineers today: askus@indium.com

Learn more: www.indium.com

ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900

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